METHOD AND DEVICE FOR SEPARATING A REINFORCING-PLATE FIXED TO A REINFORCED SEMICONDUCTOR WAFER

ABSTRACT OF THE DISCLOSURE

In a method for separating a reinforcing-plate fixed to a reinforced semiconductor wafer, the wafer includes a semiconductor wafer on which a pattern is formed and a double-side adhesive sheet having, on at least one surface thereof, a peelable adhesive layer, wherein the peelable adhesive layer is stuck to a front face of the semiconductor wafer and the reinforcing-plate is fixed to the other adhesive layer of the double-side adhesive sheet. The reinforcing-plate is separated together with the double-side adhesive sheet from the reinforced semiconductor wafer by the peeling-effect of the peelable adhesive layer of the double-side adhesive sheet. Furthermore, the reinforcing-plate is separated from an arbitrarily selected edge of the semiconductor wafer toward an edge thereof different from the above-mentioned edge. This makes it possible to separate the reinforcing-plate, without breaking the semiconductor wafer, from the reinforced semiconductor wafer to which the reinforcing-plate is fixed through the double-side adhesive sheet having the peelable adhesive layer.

Fig. 1(a) – (d)